

OCTAL 3-STATE NONINVERTING D-TYPE TRANSPARENT LATCH**DESCRIPTION**

The M74HC373-1 is an integrated circuit chip consisting of eight 3-state output D-type latches with common-enable input and output-enable input.

FEATURES

- High-fanout 3-state output : ($I_{OL}=24\text{mA}$, $I_{OH}=-24\text{mA}$)
- High-speed : 9ns typ. ($C_L=50\text{pF}$, $V_{CC}=5\text{V}$)
- Low power dissipation : 25 $\mu\text{W}/\text{package}$, max ($V_{CC}=5\text{V}$, $T_a=25^\circ\text{C}$, quiescent state)
- High noise margin : 30% of V_{CC} , min ($V_{CC}=4.5, 6\text{V}$)
- Capable of driving 60 74 LSTTL loads
- Wide operating voltage range : $V_{CC}=2\sim 6\text{V}$
- Wide operating temperature range : $T_a=-40\sim +85^\circ\text{C}$

APPLICATION

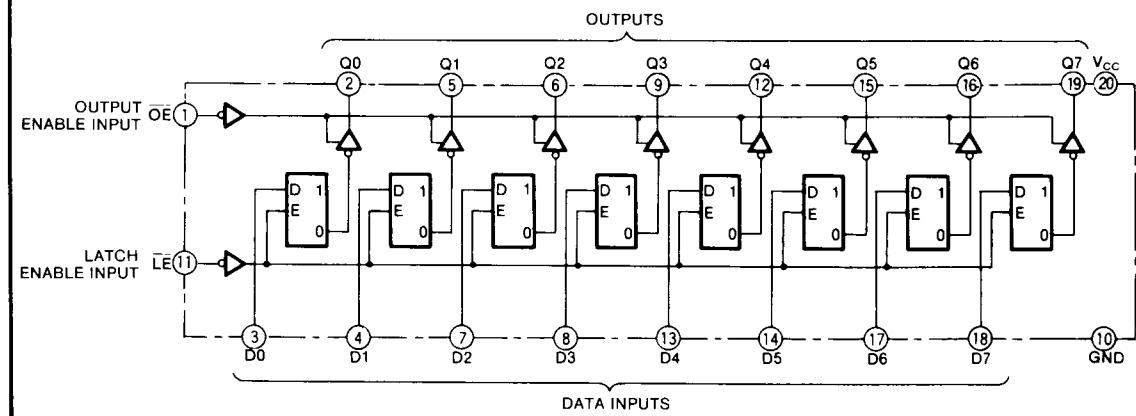
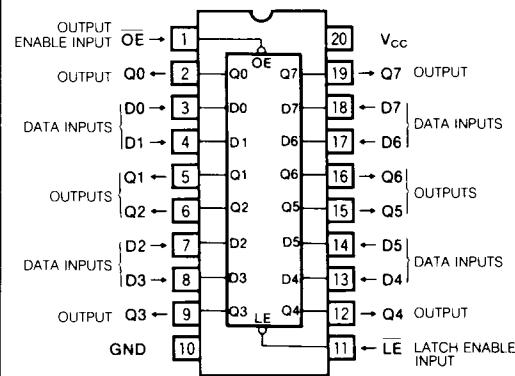
General purpose, for use in industrial and consumer digital equipment.

FUNCTION

Use of silicon gate technology allows the M74HC373-1 to maintain the low power dissipation and high noise margin characteristics of the standard CMOS logic 4000B series while giving high-speed performance equivalent to the 74LS373. The circuit is designed to suppress the increased switching noise that normally occurs at high output currents. The M74HC373-1 consists of eight D-type latches with latch-enable input LE and output-enable input OE common to all circuits.

When LE is high-level, the data input D appears at output Q through the latch and the Q state follows changes in the D state. When LE changes from high to low-level, the data immediately prior to the change at D will be stored in the latch.

Even if other inputs are changed when LE is low-level, the contents stored in the latch will not be affected.

LOGICAL DIAGRAM**PIN CONFIGURATION (TOP VIEW)**

Outline
20P4
20P2N

When OE is high-level, all outputs Q will become high-impedance states.

A version of the M74HC373-1 with the same pin connection and an inverted output, the M74HC533-1, is also available.

FUNCTION TABLE (Note 1)

Inputs			Output
OE	LE	D	Q
L	H	H	H
L	H	L	L
L	L	X	Q ⁰
H	X	X	Z

Note 1 : Q⁰ : Output state Q before LE changed.

Z : High impedance

X : Irrelevant

OCTAL 3-STATE NONINVERTING D-TYPE TRANSPARENT LATCH

ABSOLUTE MAXIMUM RATINGS ($T_a = -40\text{~}+85^\circ\text{C}$, unless otherwise noted)

Symbol	Parameter	Conditions	Ratings	Unit
V_{CC}	Supply voltage		-0.5~+7.0	V
V_I	Input voltage		-0.5~ $V_{CC}+0.5$	V
V_O	Output voltage		-0.5~ $V_{CC}+0.5$	V
I_{IK}	Input protection diode current	$V_I < 0\text{V}$	-20	
		$V_I > V_{CC}$	20	mA
I_{OK}	Output parasitic diode current	$V_O < 0\text{V}$	-20	
		$V_O > V_{CC}$	20	mA
I_O	Output current		± 50	mA
I_{CC}	Supply/GND current	$V_{CC}, \text{ GND}$	± 200	mA
P_d	Power dissipation	(Note 2)	500	mW
T_{STG}	Storage temperature		-65~+150	°C

Note 2 : M74HC373-1FP : $T_a = -40\text{~}+75^\circ\text{C}$ and $T_a = 75\text{~}85^\circ\text{C}$ are derated at -7mW/°C

RECOMMENDED OPERATING CONDITIONS ($T_a = -40\text{~}+85^\circ\text{C}$)

Symbol	Parameter	Limits			Unit
		Min	Typ	Max	
V_{CC}	Supply voltage	2		6	V
V_I	Input voltage	0		V_{CC}	V
V_O	Output voltage	0		V_{CC}	V
T_{OPR}	Operating temperature	-40		+85	°C
t_r, t_f	Input rise time, fall time	$V_{CC} = 2.0\text{V}$	0	500	ns/V
		$V_{CC} = 4.5\text{V}$	0	50	
		$V_{CC} = 6.0\text{V}$	0	30	

ELECTRICAL CHARACTERISTICS

Symbol	Parameter	Test conditions	Limits					Unit
			$V_{CC}(\text{V})$	Min	Typ	Max	Min	
V_{IH}	High-level input voltage	$V_O = 0.1\text{V}, V_{CC} = 0.1\text{V}$ $I_O = 20\mu\text{A}$	2.0	1.5			1.5	V
			4.5	3.15			3.15	
			6.0	4.2			4.2	
V_{IL}	Low-level input voltage	$V_O = 0.1\text{V}, V_{CC} = 0.1\text{V}$ $ I_O = 20\mu\text{A}$	2.0			0.5	0.5	V
			4.5			1.35	1.35	
			6.0			1.8	1.8	
V_{OH}	High-level output voltage	$I_{OH} = -20\mu\text{A}$ $V_I = V_{IL}, V_{IH}$	2.0	1.9			1.9	V
			4.5	4.4			4.4	
			6.0	5.9			5.9	
			4.5	3.83			3.70	
V_{OL}	Low-level output voltage	$I_{OL} = 20\mu\text{A}$ $V_I = V_{IH}, V_{IL}$	2.0			0.1	0.1	V
			4.5			0.1	0.1	
			6.0			0.1	0.1	
			4.5			0.44	0.53	
I_{IH}	High-level input current	$V_I = 6\text{V}$	6.0			0.1	1.0	μA
I_{IL}	Low-level input current	$V_I = 0\text{V}$	6.0			-0.1	-1.0	μA
I_{OZH}	Off-state high-level output current	$V_I = V_{IH}, V_{IL}, V_O = V_{CC}$	6.0			0.5	5.0	μA
I_{OZL}	Off-state low-level output current	$V_I = V_{IH}, V_{IL}, V_O = \text{GND}$	6.0			-0.5	-5.0	μA
I_{CC}	Quiescent supply current	$V_I = V_{CC}, \text{ GND}, I_O = 0\mu\text{A}$	6.0			5.0	50.0	μA

OCTAL 3-STATE NONINVERTING D-TYPE TRANSPARENT LATCH

SWITCHING CHARACTERISTICS ($V_{CC} = 5V$, $T_a = 25^\circ C$)

Symbol	Parameter	Test conditions	Limits			Unit
			Min	Typ	Max	
t_{TLH}	Low-to high-level and high-to low-level output transition time	$C_L = 50\text{pF}$ (Note 4)			10	ns
t_{THL}					10	ns
t_{PLH}					17	ns
t_{PHL}					17	ns
t_{PLH}					20	ns
t_{PHL}					20	ns
t_{PLZ}	Low-level and high-level output disable time ($\bar{OE} - Q$)	$C_L = 5 \text{ pF}$ (Note 4)			18	ns
t_{PHZ}					18	ns
t_{PZL}	Low-level and high-level output enable time ($OE - Q$)	$C_L = 50\text{pF}$ (Note 4)			20	ns
t_{PZH}					20	ns

SWITCHING CHARACTERISTICS ($V_{CC} = 2\sim 6V$, $T_a = -40\sim +85^\circ C$)

Symbol	Parameter	Test conditions	Limits					Unit
			25°C			-40~+85°C		
			$V_{CC}(\text{V})$	Min	Typ	Max	Min	Max
t_{TLH}	Low-to high-level and high-to low-level output transition time	$C_L = 50\text{pF}$ (Note 4)	2.0	12	60		75	ns
			4.5	5	12		15	
			6.0	4	10		13	
			2.0	18	60		75	
			4.5	5	12		15	
			6.0	4	10		13	
t_{PLH}	Low-to high-level and high-to low-level output propagation time (D - Q)	$C_L = 50\text{pF}$ (Note 4)	2.0	36	90		115	ns
			4.5	9	18		23	
			6.0	7	15		20	
			2.0	28	90		115	
			4.5	10	18		23	
			6.0	9	15		20	
t_{PHL}	Low-to high-level and high-to low-level output propagation time ($\bar{LE} - Q$)	$C_L = 50\text{pF}$ (Note 4)	2.0	32	105		130	ns
			4.5	11	21		26	
			6.0	9	18		22	
			2.0	33	105		130	
			4.5	11	21		26	
			6.0	9	18		22	
t_{PLZ}	Low-level and high-level output disable time ($\bar{OE} - Q$)	$C_L = 50\text{pF}$ (Note 4)	2.0	15	105		130	ns
			4.5	7	21		26	
			6.0	7	18		22	
			2.0	16	105		130	
			4.5	10	21		26	
			6.0	9	18		22	
t_{PZL}	Low-level and high-level output enable time ($OE - Q$)	$C_L = 50\text{pF}$ (Note 4)	2.0	22	105		130	ns
			4.5	8	21		26	
			6.0	6	18		22	
			2.0	24	105		130	
			4.5	9	21		26	
			6.0	7	18		22	
C_I	Input capacitance					10	10	pF
C_O	Off-state output capacitance $\bar{OE} = V_{CC}$					15	15	pF
C_{PD}	Power dissipation capacitance (Note 3)				44.5			pF

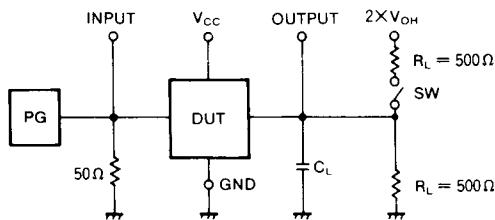
Note 3 : C_{PD} is the internal capacitance of the IC calculated from operation supply current under no-load conditions (per latch). The power dissipated during operation under no-load condition is calculated using the following formula :

$$P_D = C_{PD} \cdot V_{CC}^2 \cdot f_1 + I_{CC} \cdot V_{CC}$$

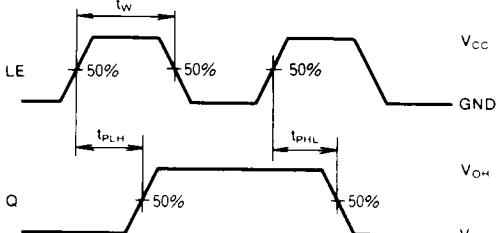
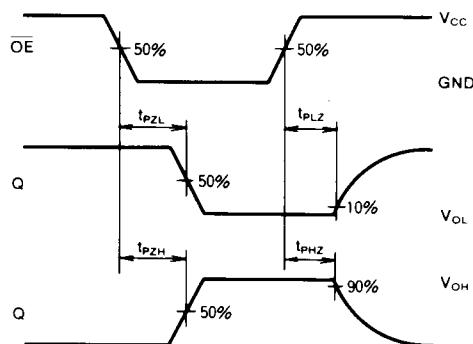
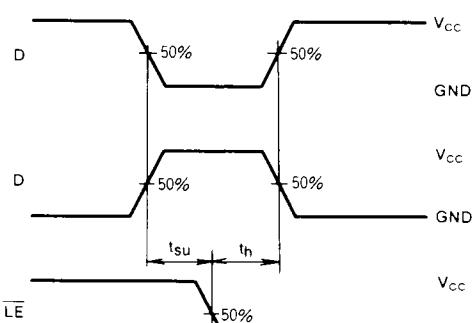
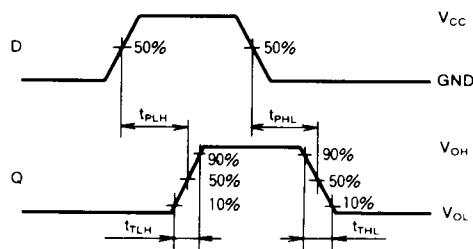
OCTAL 3-STATE NONINVERTING D-TYPE TRANSPARENT LATCH**TIMING REQUIREMENTS** ($V_{CC} = 2\sim 6V$, $T_a = -40\sim +85^\circ C$)

Symbol	Parameter	Test conditions	Limits					Unit	
			25°C			-40~+85°C			
			$V_{CC}(V)$	Min	Typ	Max	Min	Max	
t_W	Latch-enable pulse width		2.0	60	8		75		ns
			4.5	12	3		15		
			6.0	10	2		13		
t_{SU}	D setup time with respect to \overline{LE}		2.0	50	3		65		ns
			4.5	10	1		13		
			6.0	9	1		11		
t_h	D hold time with respect to \overline{LE}		2.0	25	-2		30		ns
			4.5	5	0		6		
			6.0	5	0		6		

Note 4 : Test Circuit



Parameter	SW
t_{TLH}, t_{THL}	Open
t_{PLH}, t_{PHL}	Closed
t_{PLZ}	Open
t_{PHZ}	Open
t_{PZL}	Closed
t_{PZH}	Open

(1) The pulse generator (PG) has the following characteristics (10%~90%) : $t_r=3ns$, $t_f=3ns$ (2) The capacitance C_L includes stray wiring capacitance and the probe input capacitance.**TIMING DIAGRAM**

**MITSUBISHI HIGH SPEED CMOS
PACKAGE OUTLINES**

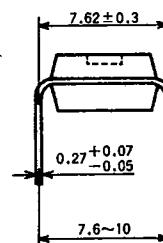
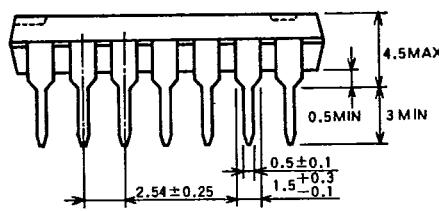
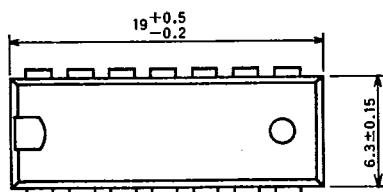
6249827 MITSUBISHI {DGTL LOGIC}

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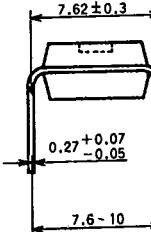
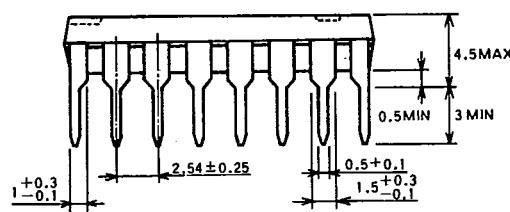
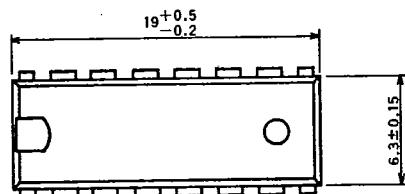
D T-90-20

TYPE 14P4 14-PIN MOLDED PLASTIC DIP

Dimension in mm

**TYPE 16P4 16-PIN MOLDED PLASTIC DIP**

Dimension in mm

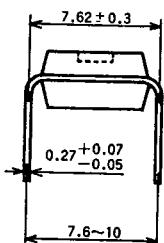
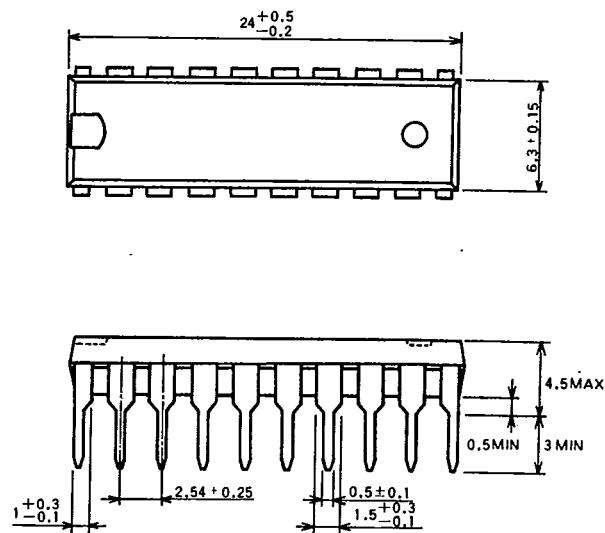


MITSUBISHI HIGH SPEED CMOS
PACKAGE OUTLINES

91D 12850 D T-90-20

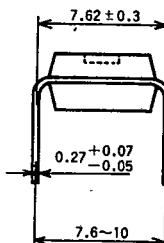
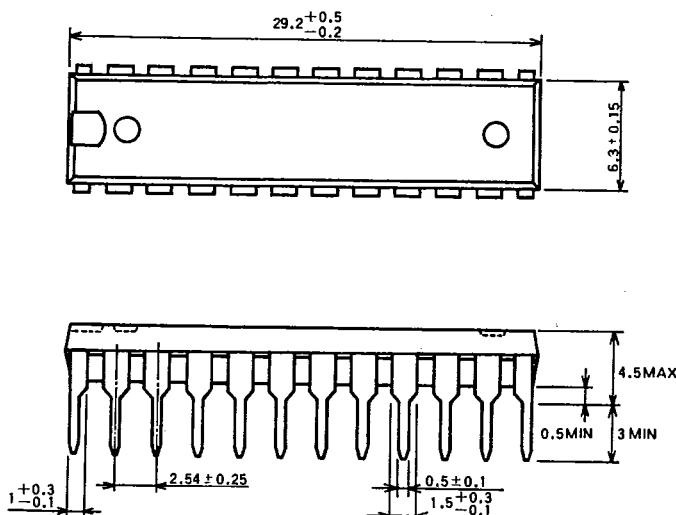
TYPE 20P4 20-PIN MOLDED PLASTIC DIP

Dimension in mm



TYPE 24P4D 24-PIN MOLDED PLASTIC DIP

Dimension in mm



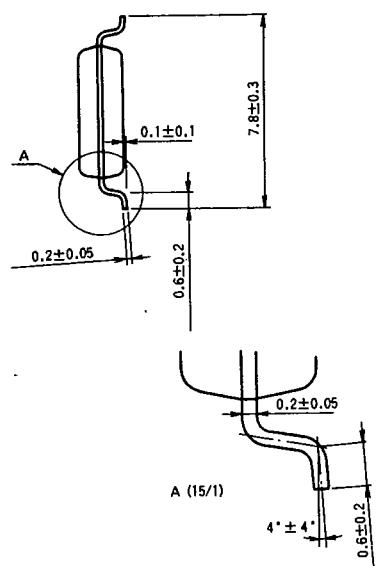
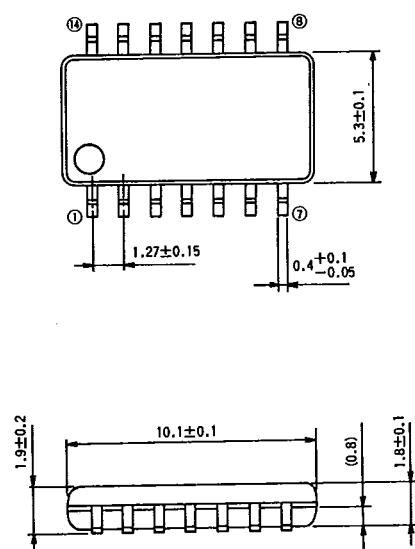
MITSUBISHI HIGH SPEED CMOS
PACKAGE OUTLINES

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91D 12851 D T-90.20

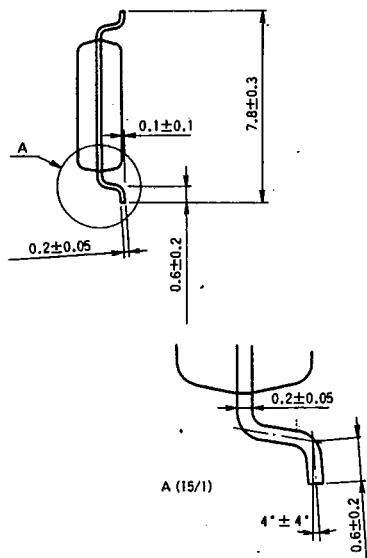
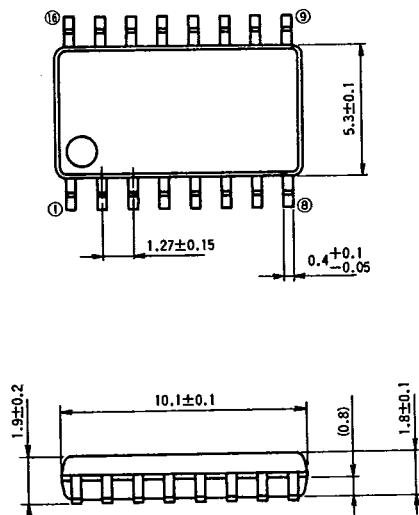
TYPE 14P2N 14PIN MOLDED PLASTIC SOP

Dimension in mm



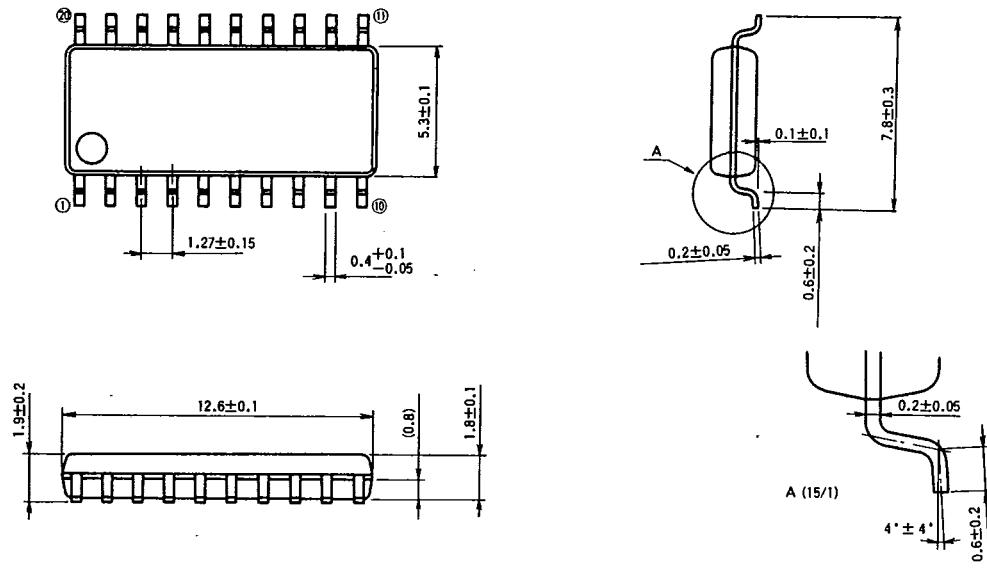
TYPE 16P2N 16PIN MOLDED PLASTIC SOP

Dimension in mm



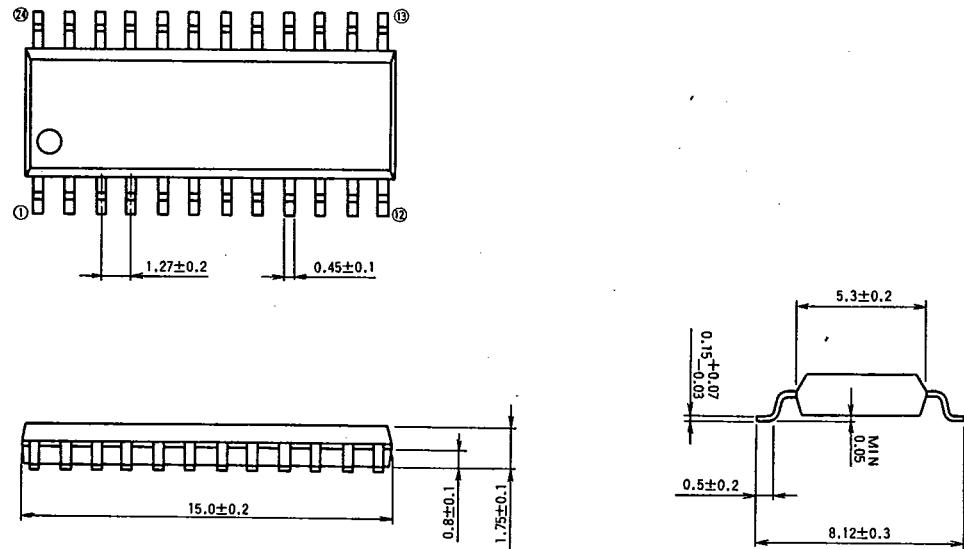
TYPE 20P2N 20PIN MOLDED PLASTIC SOP

Dimension in mm



TYPE 24P2 24PIN MOLDED PLASTIC SOP

Dimension in mm

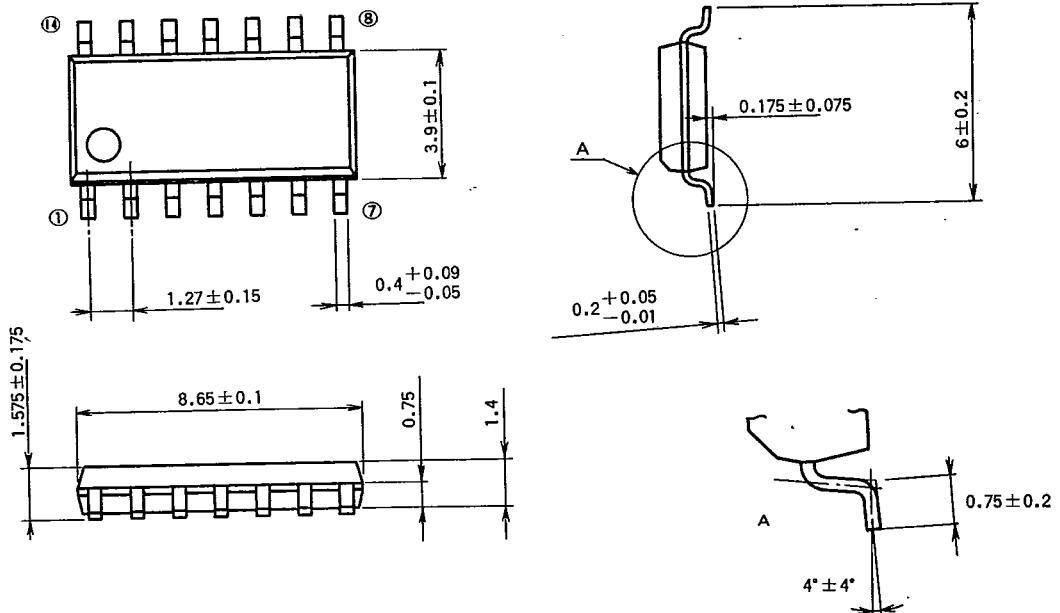


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91D 12853 D T90-20

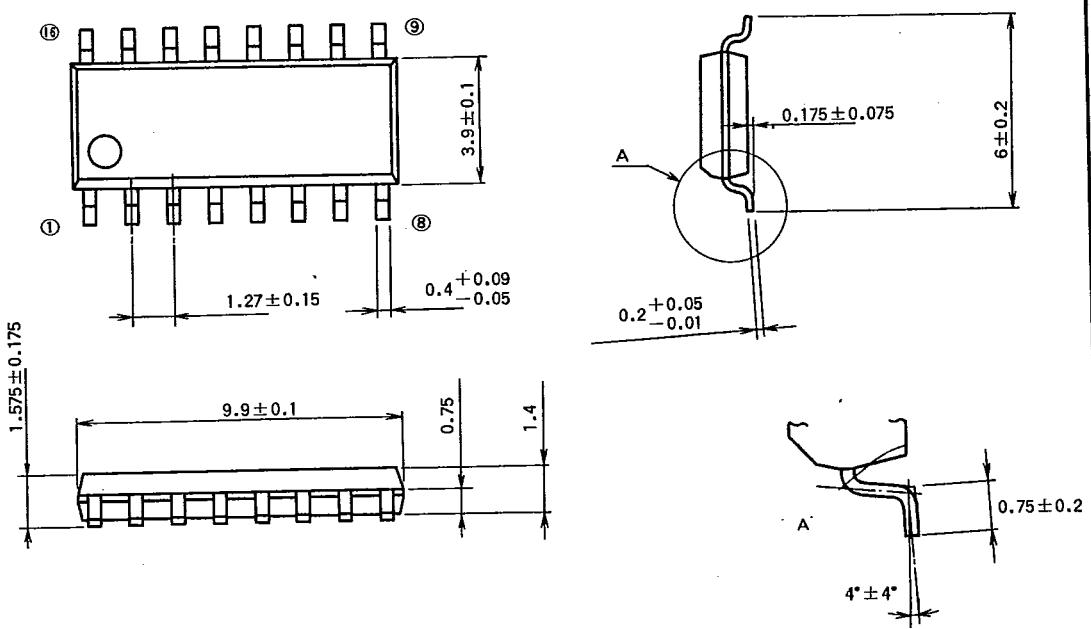
TYPE 14P2P 14-PIN MOLDED PLASTIC SOP(JEDEC 150mil body)

Dimension in mm



TYPE 16P2P 16-PIN MOLDED PLASTIC SOP(JEDEC 150mil body)

Dimension in mm



PACKAGE OUTLINES

6249827 MITSUBISHI (DGTL LOGIC)

91D 12854 D T-90-20

TYPE 20P2V 20-PIN MOLDED PLASTIC SOP(JEDEC 300mil body)

